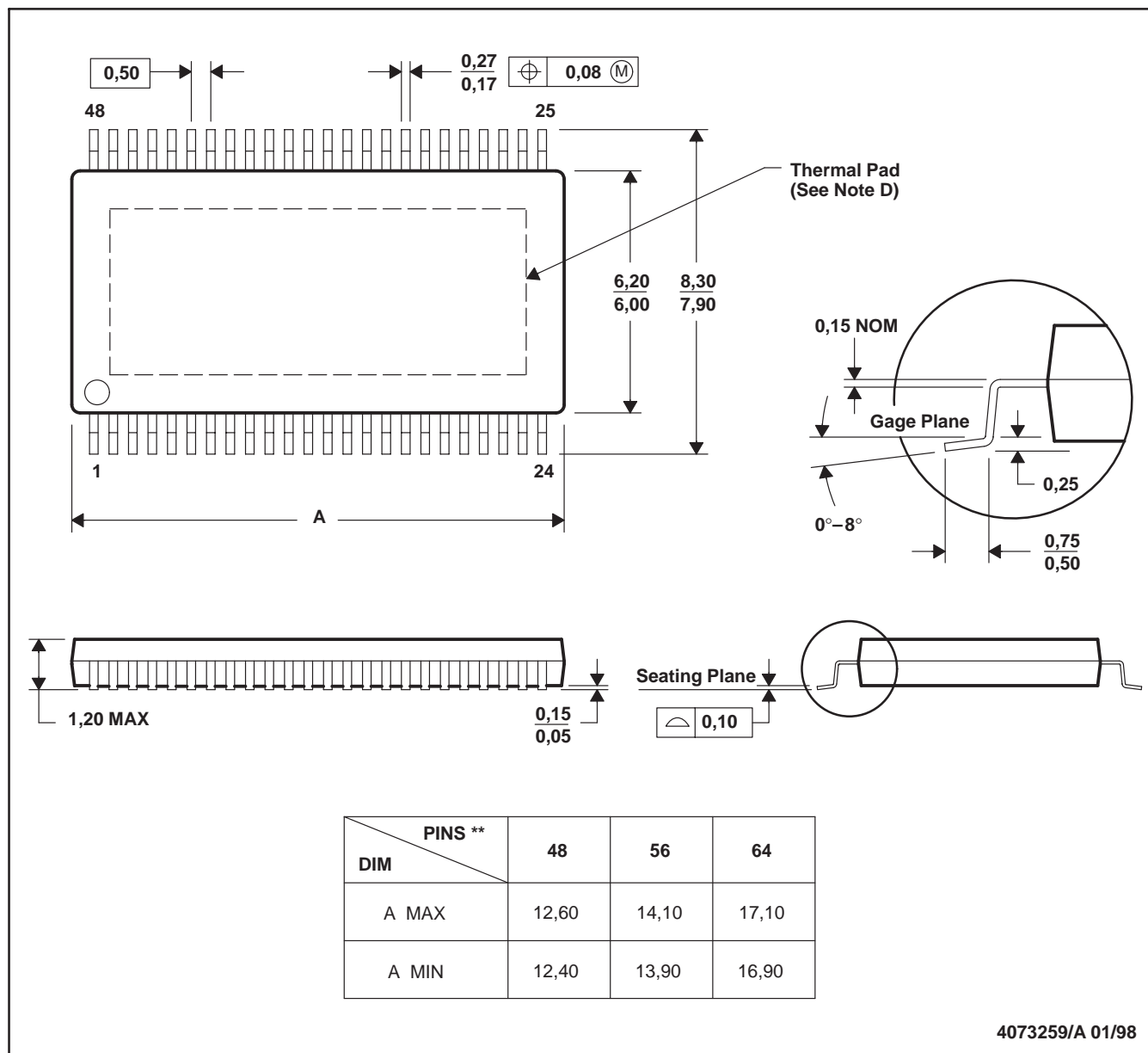


DCA (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

48-PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
 E. Falls within JEDEC MO-153

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